

Bluetooth Low Energy Module (BT5.0)



FCC ID: 2ABRUDBLEM205

Key Features

- Bluetooth 4 and 5 low energy
- Powerful ARM Cortex-M4F processor
 - Clock speed: up to 48MHz
 - 352KB of In-System programmable flash with 8KB cache
 - 80KB SRAM
 - 8KB of cache SRAM
 - 2-Pin cJTAG and JTAG debugging
 - Support Over-the-Air upgrade (OTA)
 - Ultra-Low power sensor controller with 4KB of SRAM
 - 31 GPIOs
 - 4 x 32-Bit or 8 x 16-Bit general purpose timer
 - 12-Bit ADC, 200 kSamples/s, 8 channels
 - 2 x comparator with internal reference DAC
 - Programmable current source
 - 2 x UART
 - 2 x SSI (SPI, MICROWIRE, TI)
 - IIC, IIS
 - Real-Time-Clock (RTC)
 - AES 128- and 256-bit crypto accelerator
 - ECC and RSA public key hardware accelerator
 - SHA2 accelerator (Full suite up to SHA-512)
 - True Random Number Generator (TRNG)
 - Capacitive sensing, up to 8 channels
 - Integrated temperature and battery monitor
 - On-Chip buck DC/DC converter
- RF performance
 - TX power: -21dBm to 5dBm
 - RX sensitivity: up to -105dBm (LE coded PHY)
- Communication range: about 250 meters (LOS) – Long Range Mode
- Antenna: PCB antenna, 1.71 dBi gain
- Size: 22.95 mm x 15 mm x 2.1 mm (With Shielding)
- Ultra low power consumption:
 - Shutdown: 120nA (Wake up on external events)

- Standby: 0.95uA (RTC running and RAM/CPU retention)
- RX current: 6.9mA
- TX current @ 0dBm: 7.4mA
- TX current @ 5dBm: 9.7mA
- BQB, FCC, CE, RoHS compliant

Descriptions

BDE-BLEM205 is a Bluetooth 4 and 5 single-mode compliant Bluetooth low energy module targeted at low power sensors and PC/Phone accessories.

BDE-BLEM205 highly integrates Bluetooth Low Energy radio, stack, profile and applications in a SoC, without the need of using an external MCU. The module also offers flexible hardware interfaces for the sensor application.

It enables ultra-low power connectivity and data transfer for the applications that are sensitive to power consumption, size and cost.

Block Diagram

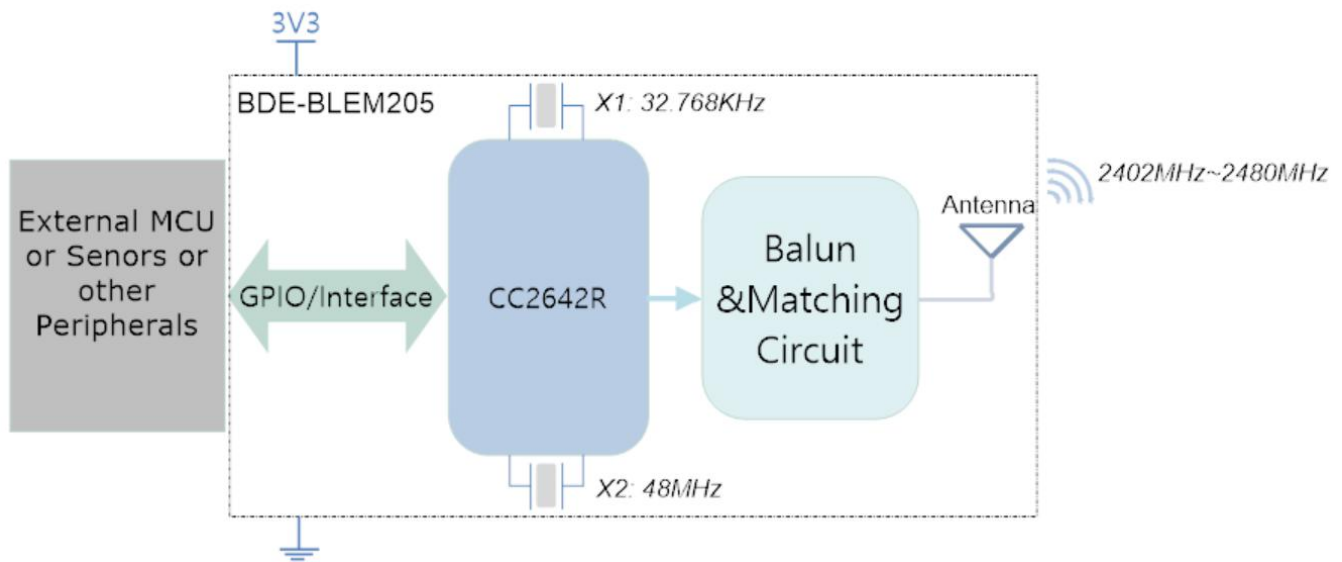


Fig. 1: The Block Diagram of BDE-BLEM205

Applications

- Medical devices
- Sports and fitness equipment
- Home electronics
- Mobile and PC accessories
- Industry automation

Electrical Characteristics

- Absolute maximum rating

Rating	Min	Typ	Max	Unit	Notes
Storage Temperature	-40	-	125	°C	
VDD	-0.3	-	4.1	V	
Other Digital Terminals	-0.3	-	$V_{DD5}+0.3 \leq 4.1$	V	
Voltage on ADC input	-0.3	-	V _{DD5}	V	Voltage scaling enabled
	-0.3	-	1.49	V	Voltage scaling disabled, internal reference
	-0.3	-	$V_{DD5}/2.9$	V	Voltage scaling disabled, V _{DD5} as reference
RF pin	-	-	5	dBm	

- Recommended operating conditions

Rating	Min	Typ	Max	Unit
Operating Temperature	-40	-	85	°C
VDD	1.8	3.3	3.8	V

Pinout

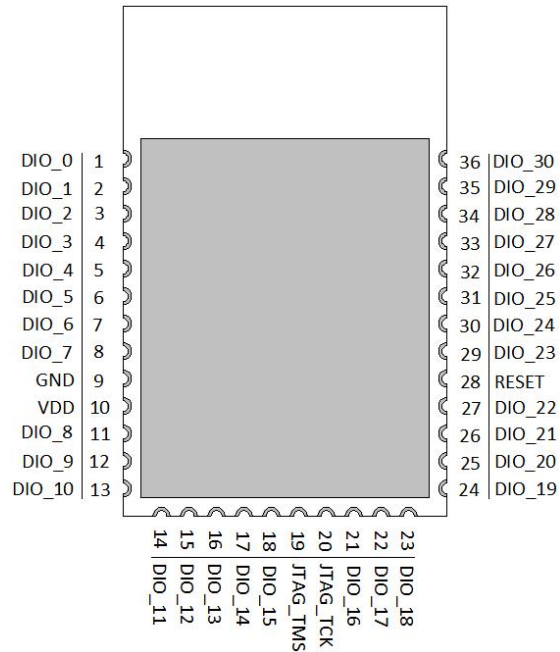


Fig. 2: The pinout of BDE-BLEM205 (TOP VIEW)

Table 1: Pin definitions of BDE-BLEM205

Pin Number	Pin Name	Definitions
1	DIO_0	GPIO, Sensor Controller
2	DIO_1	GPIO, Sensor Controller
3	DIO_2	GPIO, Sensor Controller
4	DIO_3	GPIO, Sensor Controller
5	DIO_4	GPIO, Sensor Controller
6	DIO_5	GPIO, Sensor Controller, high-drive capability
7	DIO_6	GPIO, Sensor Controller, high-drive capability
8	DIO_7	GPIO, Sensor Controller, high-drive capability
9	GND	Power Ground
10	VDD	Power Supply
11	DIO_8	GPIO
12	DIO_9	GPIO
13	DIO_10	GPIO
14	DIO_11	GPIO
15	DIO_12	GPIO
16	DIO_13	GPIO
17	DIO_14	GPIO
18	DIO_15	GPIO
19	JTAG_TMS	JTAG TMS, high-drive capability

20	JTAG_TCK	JTAG TCKC
21	DIO_16	GPIO, JTAG_TDO, high-drive capability
22	DIO_17	GPIO, JTAG_TDI, high-drive capability
23	DIO_18	GPIO
24	DIO_19	GPIO
25	DIO_20	GPIO
26	DIO_21	GPIO
27	DIO_22	GPIO
28	RESET	Reset, active-low
29	DIO_23	GPIO, Sensor Controller, Analog
30	DIO_24	GPIO, Sensor Controller, Analog
31	DIO_25	GPIO, Sensor Controller, Analog
32	DIO_26	GPIO, Sensor Controller, Analog
33	DIO_27	GPIO, Sensor Controller, Analog
34	DIO_28	GPIO, Sensor Controller, Analog
35	DIO_29	GPIO, Sensor Controller, Analog
36	DIO_30	GPIO, Sensor Controller, Analog

Overall Dimensions

Fig. 3 shows the overall dimensions of BDE-BLEM205. The module measures 22.95mm long by 15mm wide by 2.1mm high with the shield.

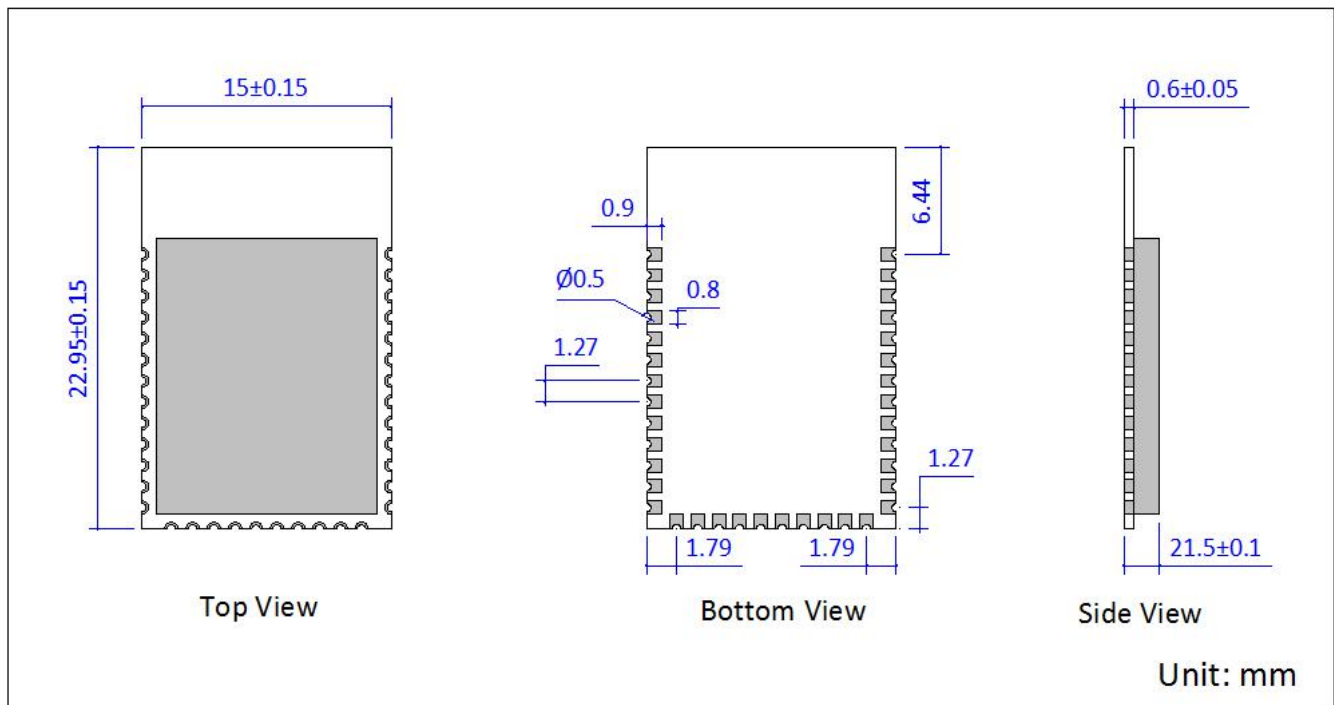


Fig. 3: Overall Dimensions of BDE-BLEM205

Module Location

In order to get a fine performance when integrate the module to your product, it is advised to use the recommended module location to the respective PCB.

■ Location in X-Y plane

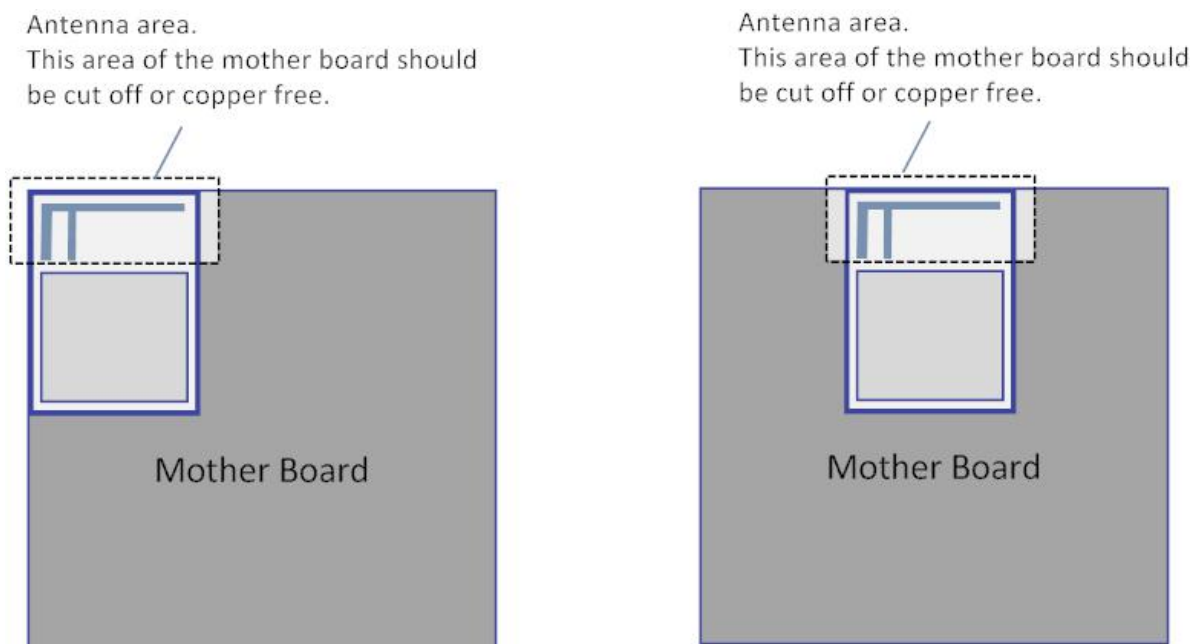


Fig. 4: Recommended location in X-Y plane

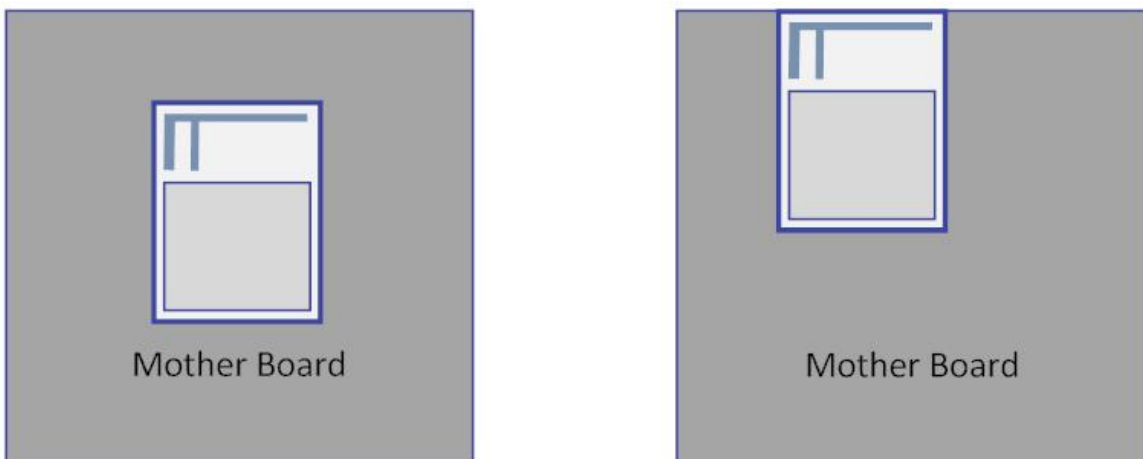


Fig. 5: Not recommended location in X-Y plane

■ Location in Z plane

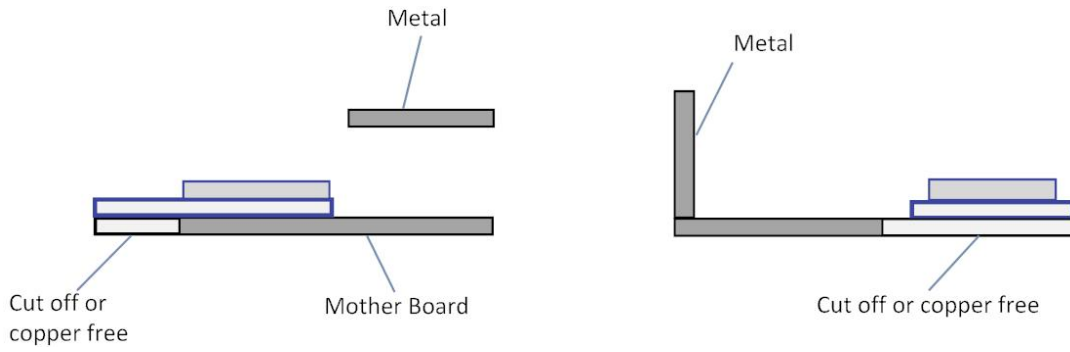


Fig. 6: Recommended location in Z plane

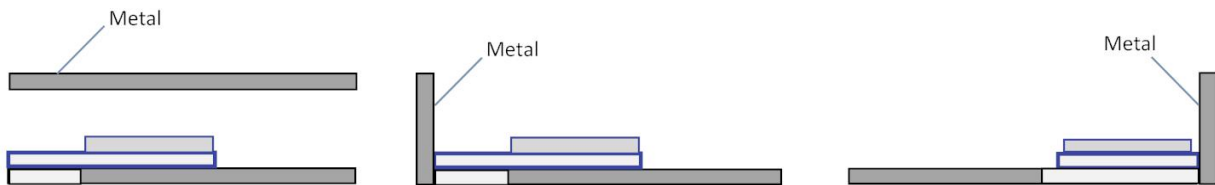


Fig. 7: Not recommended location in Z plane

Typical Solder Reflow Profile

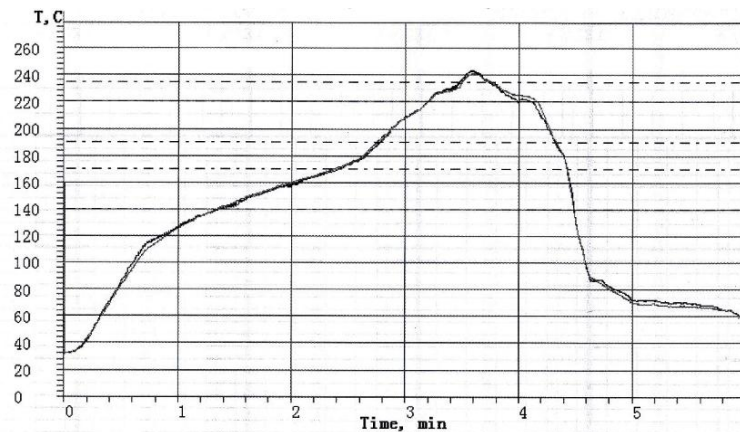


Fig. 8: Typical Solder Reflow Profile

Package Information



Fig. 9: Package

FCC statements

This device complies with part 15 of the FCC rules. Operation is subject to the following two conditions:

- (1) this device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation.

NOTE: The manufacturer is not responsible for any radio or TV interference caused by unauthorized modifications or changes to this equipment. Such modifications or changes could void the user's authority to operate the equipment.



Contacts

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